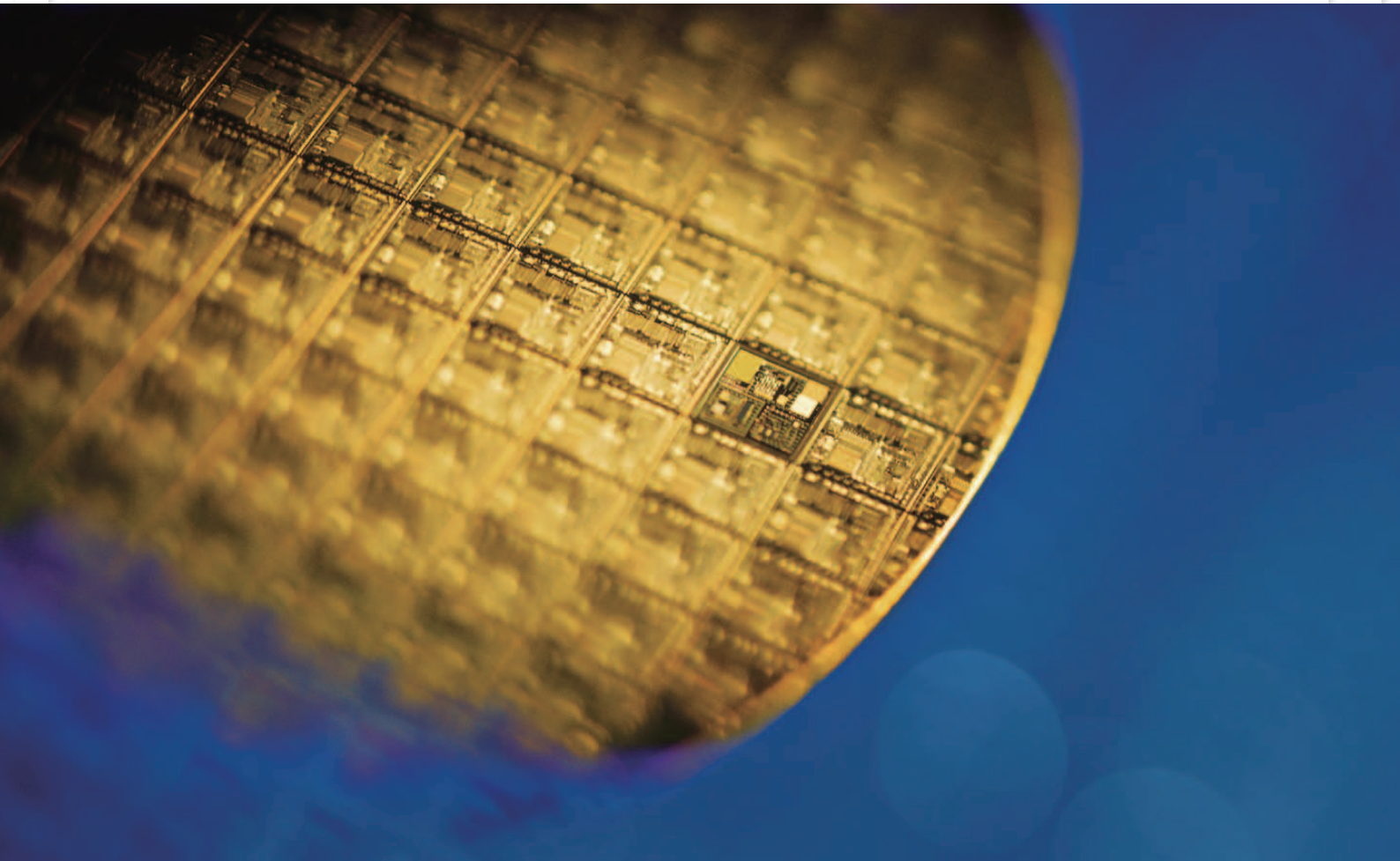


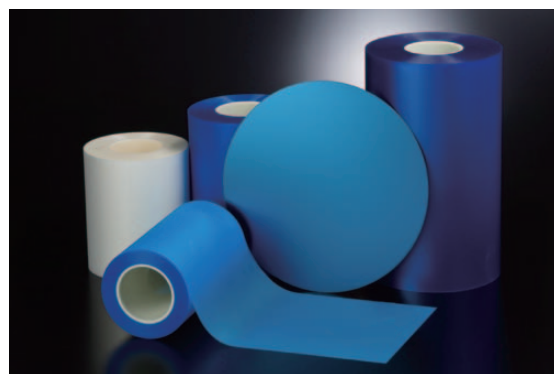
# **FURUKAWA AT-TAPES** **for Semiconductor Process**



**FURUKAWA ELECTRIC**

# BACKGRINDING TAPE

This tape is designed for surface protection of semiconductor wafers during the backgrinding process. Our backgrinding tape development has advanced to meet the needs of changing semiconductor packaging trends, such as reduced wafer thickness, increased WLCSP bump height and newly-developed processes.



## ● SP Series (UV Tape for Wafer Backgrinding)

### Features

- Reduced wafer breakage during the backgrinding process by using shock-absorbing properties of our tape.
- Easily detached from wafer without stress after UV irradiation, suitable for extremely thin and/or large wafer.
- Lower impurities allows for higher levels of wafer cleanliness.
- Excellent etching-durability makes resistless etching processes possible.

### Lineup

- Standard types
- For bumped wafer
- For thinned wafer
- Heat resistance type
- For active surface
- Etching-durable type

## ● CP Series (Non-UV Tape for Wafer Backgrinding)

### Features

- Reduced wafer breakage during the backgrinding process by using shock-absorbing properties of our tape.
- Developed for easy de-taping from thinned wafer without stress.
- Lower impurities allows for higher levels of wafer cleanliness.

### Lineup

- Standard type
- For thinned wafer
- For DDF process

Purpose		BACKGRINDING TAPE	
Name		SP Series	CP Series
Features		UV tape	Non-UV tape
Application		Si and/or compound wafer	Si wafer
Adhesion	Before UV (N/25mm)	1 – 8	0.3 – 1.0
	After UV (N/25mm)	0.1 – 2.0	
Appearance		Colorless/ Translucence blue	Translucence blue

The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

# DICING TAPE

This tape is designed for holding semiconductor wafers and packages during the dicing process while mounted to ring frames. FURUKAWA's dicing tape is used in wide areas, not only semiconductor wafer and packages, but also ceramics, glass, sapphire and so on.



## ● UC Series (UV Tape for Wafer Dicing)

### Features

- High adhesion of UV tape reduces die-fly.
- Easy die pick up without stress after UV irradiation, suitable for thinned large die.
- Stable pick up, not depending on surface variation.
- Lower impurities allows for higher levels of wafer cleanliness.

### Lineup

- Standard type
- For small die
- For thinned wafer
- Easy de-taping
- For glass
- For back side chipping
- For DAF sheet

## ● FC Series (UV Tape for Package Dicing)

### Features

- Reduced package-fly by suitable tack.
- Easy die pick up, BGA, QFN, and other package types, after UV irradiation.
- Compatible with laser and ink marks by using adjusted adhesion.

### Lineup

- Standard type
- Reduced Strings
- For preserving laser mark appearance
- Anti-ESD type

Purpose		DICING TAPE	
		UC Series	FC Series
Name		UC Series	FC Series
Features		UV tape	UV tape
Application		Si and/or compound wafer	Package
Adhesion	Before UV (N/25mm)	1 – 10	3 – 12
	After UV (N/25mm)	0.1 – 0.6	0.2 – 1.0
Appearance		Translucence	Translucence

The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

## Acquirement of ISO 9001 Certification

## AT Products Division



Furukawa Electric AT Products Division acquired the ISO 9001 certification for Global Quality Management System about the design, development and manufacture of tapes for semiconductor processing.

## Acquirement of ISO 14001 Certification

## Hiratsuka Works, Mie Works



Furukawa Electric recognizes that preservation of the global environment is a critical issue for society, and shall incorporate consideration of environmental preservation issues into every phase of corporate activity, to contribute forwards the sustainable development of prosperous and bright society.



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